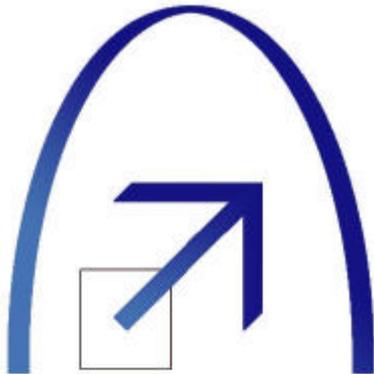


collocated with
ICSE 2005

ACM Symposium on

SOFTWARE VISUALIZATION

<http://www.softvis.org>



ST. LOUIS

14 - 15 May, 2005
Saint Louis, Missouri, USA

Sponsored by:

ACM SIGCHI, SIGGRAPH, SIGPLAN and SIGSOFT, and in cooperation with ACM SIGCSE.

Deadlines

Paper submission: Dec. 1, 2004

Notification of acceptance: Jan. 21, 2005

Final papers due: Feb. 21, 2005

Venue

SoftVis '05 is collocated with the International Conference on Software Engineering ICSE'2005 in Saint Louis. For more details on registration, hotel and travel information, please see the [ICSE 2005](http://www.icse2005.org) web page.

Student Travel

The Conference Attendance Program for Students ([CAPS](http://www.sigsoft.org/caps)) provides some financial support to graduate students, enabling them to attend SIGSOFT-sponsored conferences. The SIGPLAN Professional Activities Committee ([PAC](http://www.sigplan.org/pac)) provides support for registration fees and shared accommodation expenses for student attendance at a SIGPLAN sponsored conference where the applicant is to present a paper, is co-author of a paper on the program, or is participating in a student poster session.

More Information

For more information and questions about the SoftVis '05 Symposium, please send email to [Steve Reiss \(spr@cs.brown.edu\)](mailto:spr@cs.brown.edu).

Software visualization encompasses the development and evaluation of methods for graphically representing different aspects of software, including its structure, its abstract and concrete execution, and its evolution. The goal of this symposium is to provide a forum for researchers from different backgrounds (HCI, software engineering, programming languages, visualization, computer science education) to discuss and present original research on software visualization.

SoftVis '05 is the second meeting in a planned series of biennial conferences. Our objective is to continue to make the SoftVis series the premier venue for presenting all types of research on software visualization.

Papers

We seek theoretical as well as practical papers on applications, techniques, tools and case studies. Topics of interest include, but are not restricted to, the following:

- Visualization of algorithms, including numerical, geometric, genetic and distributed algorithms
- Visualization in software engineering, e.g. UML diagrams
- Visualization-based software in computer science and software engineering education
- Integration of software visualization tools and development environments
- Program visualization
- Protocol and log visualization (security, trust)
- Visualization of parallel programs
- Visualization of the software development process
- Visualization of data and processes in applications
- Graph drawing algorithms for software visualization
- Visualization of data base schemes
- Visual debugging
- 3D software visualization
- Software visualization on the internet
- Program analyses and visualization
- Empirical evaluation of software visualization system effectiveness
- Visualization of Web Services
- Visualization of workflow and business processes

Papers should represent original, unpublished results and will be rigorously reviewed by the international Program Committee. Papers must be in standard ACM 2-column format and cannot exceed 10 pages in total length. Authors should prepare and electronically submit a PDF version of their paper. Videos not exceeding 5 minutes in length can accompany a paper submission. Papers are due **December 1, 2004**. Further details on precise submission guidelines are available on the conference Web page at <http://www.softvis.org/softvis05>.

Symposium Organizers

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Program Co-Chairs: Tom Naps, University of Wisconsin-OshKosh, USA

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